

HIGH-SPEED COMPRESSION INTERPOSER

(0.80 mm) .0315" AND (1.00 mm) .0394" PITCH

FEATURES & BENEFITS

- Dual compression contacts or single compression with solder balls
- BeCu Micro-formed contacts
- Performance up to 14 Gbps (ZAX Series) and 56 Gbps (ZA8H Series)
- Low-profile body height for a short signal path
- Highly customizable solutions
- Visit samtec.com?ZRDP for ultra-low profile Z-Ray[®] cable assembly



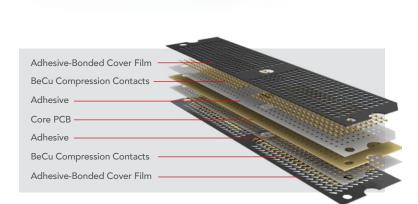


Solder Ball Option

BeCu Compression Contacts

Design & Construction

- One-piece design assembled into rugged low profile FR4 substrate under high pressure and temperature
- Built standard with a 1 mm board-to-board thickness
- Contacts are designed using BeCu foils that have been formed into the "beam" structure



PERFORMANCE SPECIFICATIONS

		Single Compression w/ Solder Balls		Dual Compression		
Series		ZA8	ZA1	ZA8	ZA1	ZA8H
Pitch		0.80 mm	1.00 mm	0.80 mm	1.00 mm	0.80 mm
Max Row		25	20	50	58	50
Max Column		25	20	50	58	50
Thickness	Kapton Core	N/A	N/A	0.33 mm	0.33 mm	0.33 mm
	FR4 Core	1.00 to 3 mm	1.00 to 3 mm	0.5 to 3 mm	0.5 to 3 mm	N/A
Thickness Tolerance	Kapton Core	N/A	N/A	±5%	±5%	±5%
	FR4 Core	±10%	±10%	±10%	±10%	N/A
Deflection / Normal Force per Pin		0.20 mm / 30g				
Operating Temperature		-55° C to $+105^{\circ}$ C (Single Cycle only above 85° C)				

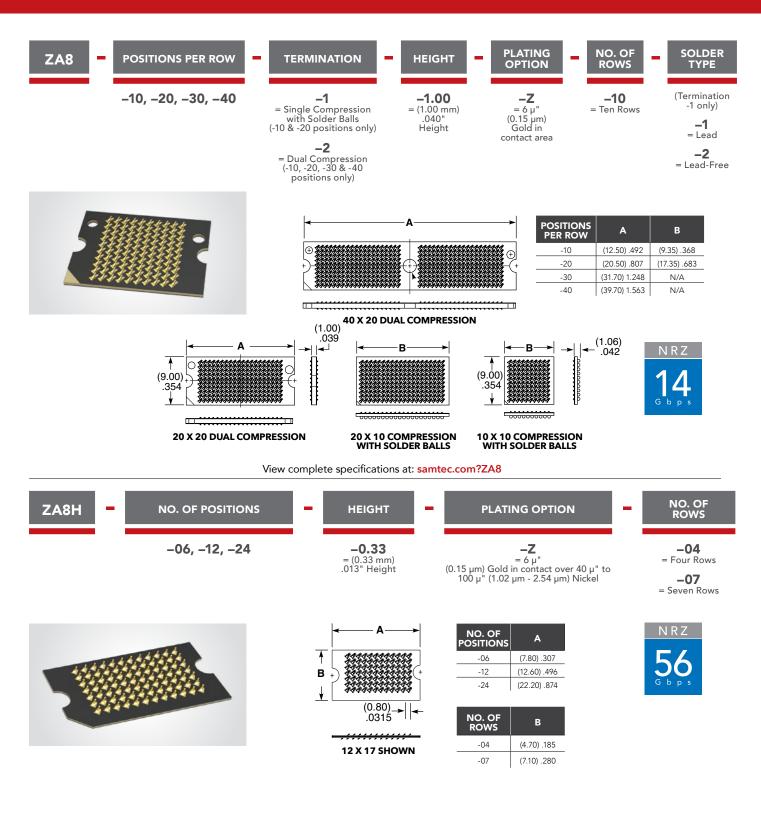
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Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.





(0.80 mm) .0315" PITCH • HIGH-SPEED COMPRESSION INTERPOSER



Notes: Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?ZA8H

samtec.com/ZRAY

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Samtec: ZA8-10-2-1.00-Z-10